

VTech Telecommunications Ltd.

20 April, 2007

Intertek Testing Services Hong Kong Ltd.
2/F, Garment Centre,
576 Castle Peak Road,
Kowloon, Hong Kong.

To whom it may concern,

“Purpose of the Change” Letter

The changes are applied to models : 6031, 6032, 6041, 6042, 6043, 6051, 6052, 6053,
FCC ID: EW780-6044-00 and IC:1135A-80615400.

The details of the change are as below:

- a. Handset main board PCB is changed from 4-layer FR4 to 2-layer FR4. There are some changes in the PCB layout.
- b. There are some changes in the Handset RF boards - only moving some traces from top layer to bottom layer. There is no change on the RF schematic diagram or component values.
- c. There is no change on the Base unit.

The change does not intend for maximum power and change on field strength ratings. The main purpose is to save cost by changing from 4-layer PCB to 2-layer PCB.

Regards,



Ricky Ng
Technical Manager